ABSTRACT

fixed resistor network has an insulating substrate, a plurality of film resistors arranged on a top surface of the insulating substrate, terminal electrodes formed for the film resistors on each lengthwise sidewall of the insulating substrate at a given pitch along the sidewall, and recesses provided between the terminal electrodes. The occurrence of solder bridges between the terminal electrodes during solder mounting and the occurrence of chipping in the terminal-electrode-forming areas between the recesses on the lengthwise sidewall are both reduced by making the width of the recesses along the lengthwise sidewall either 0.44 to 0.48 times or 0.525 to 0.625times the pitch.

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